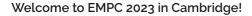
CONTACT



The European Microelectronics Packaging Conference (EMPC 2023) is the premier international conference for microelectronics packaging, organised by IMAPS and IEEE-EPS.

The conference program will focus on industrial needs and trends and on academic long-term solutions. The event brings together researchers, innovators, technologists, business and marketing managers with an interest in semiconductor packaging

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The content must be original (previously unpublished), non-confidential and non-commercial Maximum abstract length: 300-500 words. Figures with appropriate captions, and references, can be included, they do not count in the word limit. More information can be found at www.empc2023.org.

DEADLINE

for abstract submission is January 31, 2023

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125 High Street Chesterton Cambridge CB4 1NL, UK office@imaps.org.uk

Conference Venue

Genome Campus Hinxton, Cambridge, CB10 1SA **England**

Conference Chair:

Professor Anne Vanhoestenberghe King's College London, UK

Technical Chair:

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- Technologies
- System in Package
- Equipment Developments

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- Wafer Level Packaging
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- Failure Modes (e.g. Ageing, Thermal Shock)
- Material Handling
- · Cooling Systems

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- Electrical Characterisation
- Packaging Developments

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